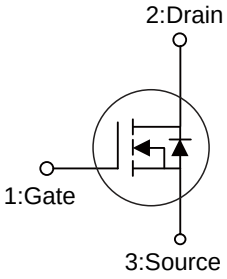
■ PRODUCT CHARACTERISTICS

V_{DSS}	500V
$R_{DS(ON)}$Typ(@V_{GS}=10V)	0.51Ω
Qg@typ	32nC
I_D	10A

Symbol



■ APPLICATIONS

* High efficiency switch mode power supplies
* Electronic lamp ballasts based on half bridge
* LED power supplies



TO-252

■ FEATURE

* High Switching Speed
* Improved dv/dt capability

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT10N50D	TO-252	2500 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS(T_A=25°C,unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GSS}	±30	V
Drain Current Continuous(@V_{GS}=10V ,T_A=25°C)	I_D	10	A
Drain Current Pulsed	I_{DM}	40	A
Avalanche Energy *	E_{AS}	890	mJ
Peak Diode Recovery dv/dt	dv/dt	5.0	V/ns
Power Dissipation	P_D	52	W
Junction Temperature	T_J	+150	°C
Storage Temperature	T_{STG}	-55~ +150	°C

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Ambient	R_{thJA}	100	°C/W
Junction to Case	R_{thJC}	2.4	°C/W

Note: * EAS condition: T_J=25°C ,V_{DD}=50V,V_G=10V ,L=10mH,R_g =25Ω

■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V_{DSS}	V_{GS}=0V,I_D=250μA	500	-	-	V
Drain to Source Leakage Current	I_{DSS}	V_{DS}=500V,V_{GS}=0V	-	-	1	μA
Gate to Source Forward Leakage	$I_{GSS(F)}$	V_{DS}=0V, V_{GS}=+30V	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	V_{DS}=0V, V_{GS}=-30V	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	V_{GS}=10V,I_D=5A	-	0.51	0.57	Ω
Gate Threshold Voltage	$V_{GS(TH)}$	V_{DS}=V_{GS},I_D=250μA	2	-	4	V
Dynamic characteristics						
Gate capacitance	R_g	V_{GS}=0V,V_{DS}=0V ,f=1.0MHz	-	2.7	-	Ω
Forward Transconductance	g_{fs}	V_{DS}=10V,I_D=1A	-	6	-	S
Input Capacitance	C_{iss}	V_{DS}=25V,V_{GS}=0V f=1.0MHz	-	1600	-	pF
Output Capacitance	C_{oss}		-	119	-	pF
Reverse Transfer Capacitance	C_{rss}		-	3	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	I_D=10A, V_{DS}=250V R_G=25Ω ,V_{GS}=10V	-	14	-	ns
Rise Time	t_r		-	20	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	56	-	ns
Fall Time	t_f		-	25	-	ns
Total Gate Charge	Q_g	I_D=10A, V_{DS}=250V V_{GS}=10V	-	32	-	nC
Gate to Source Charge	Q_{gs}		-	11.5	-	nC
Gate to Drain("Miller") Charge	Q_{gd}		-	8.5	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I_S		-	-	10	A
Maximum Pulsed Current(Body Diode)	I_{SM}		-	-	40	A
Diode Forward Voltage	V_{SD}	I_{SD}=1A, V_{GS}=0V	-	0.72	1.2	V
Reverse Recovery Time	t_{rr}	I_{SD} =10 A, T_J=25 °C dI/dt=100A/μs	-	335	-	ns
Reverse Recovery Charge	Q_{rr}		-	3000	-	nC

■ TYPICAL CHARACTERISTICS

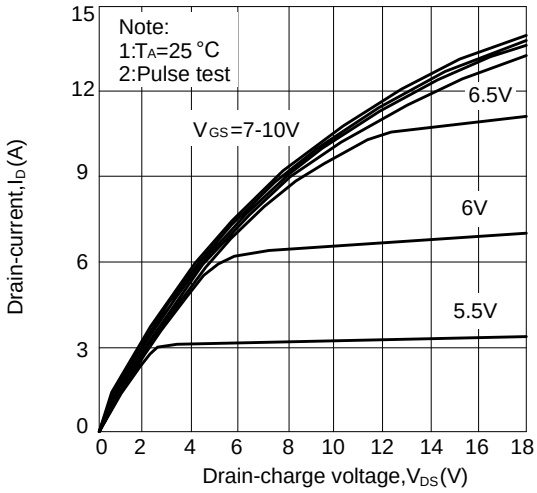


Figure 1:Drain current vs.drain-source voltage

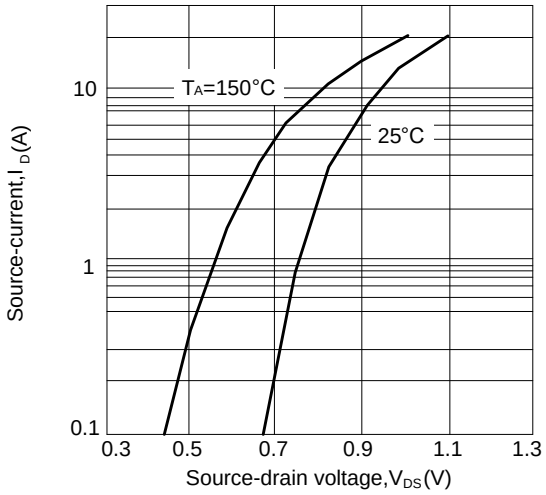


Figure 2:Source currentvs.source-drain

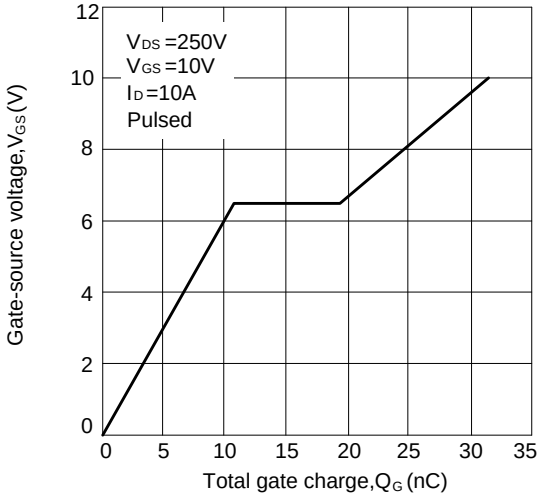


Figure 3:Gate charge characteristics

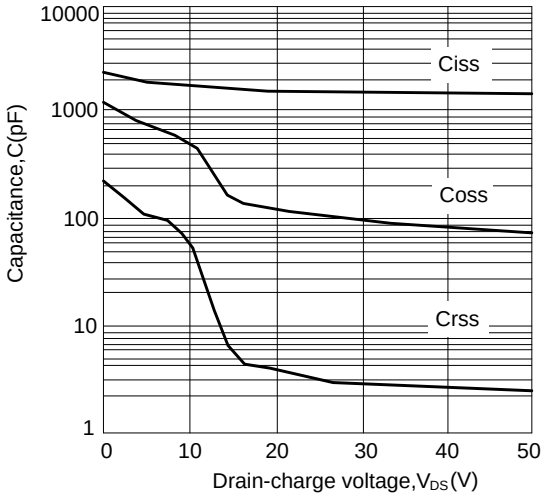


Figure 4:Capacitance characteristics

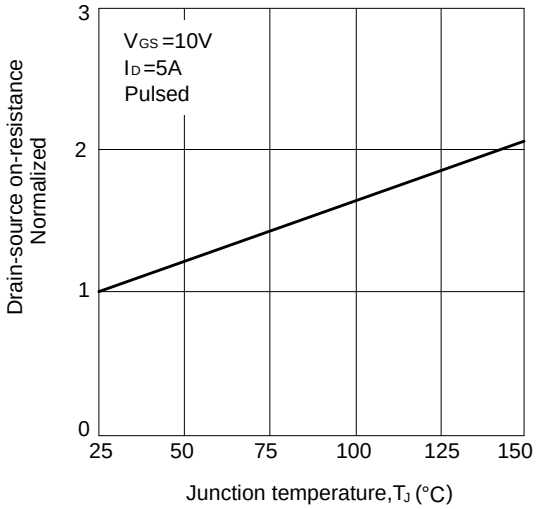


Figure 5:Drain-source on-resistance vs. junction temperature

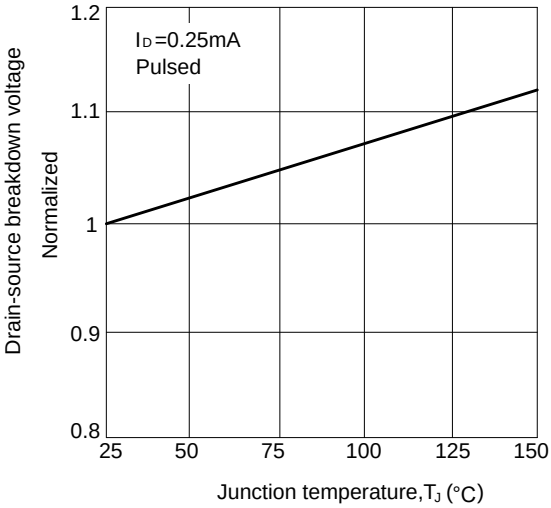


Figure 6:Breakdown voltage vs. junction temperature

■ TYPICAL CHARACTERISTICS(Cont.)

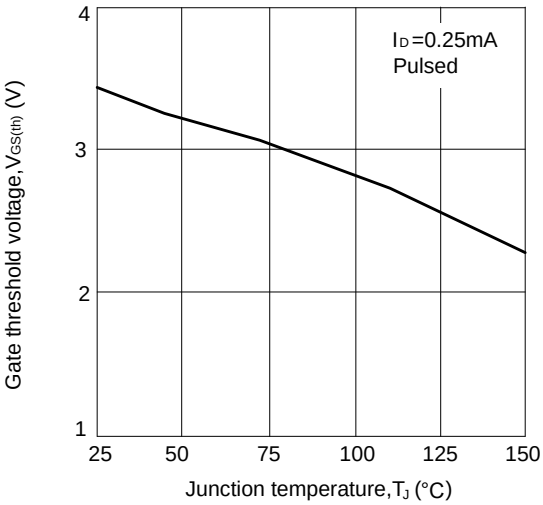


Figure 7:Gate threshlid voltage vs junction temperature

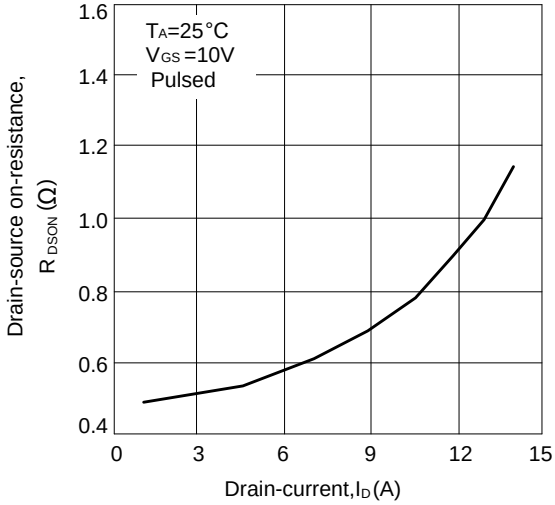


Figure 8:Drain-source on-resistance vs. drain-current

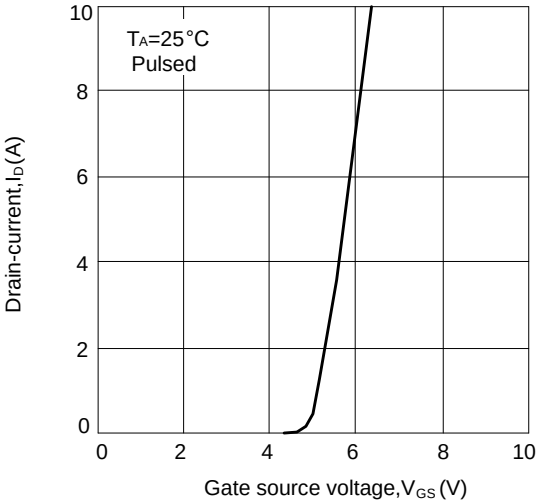


Figure 9:Drain-current vs. gate-source Voltage

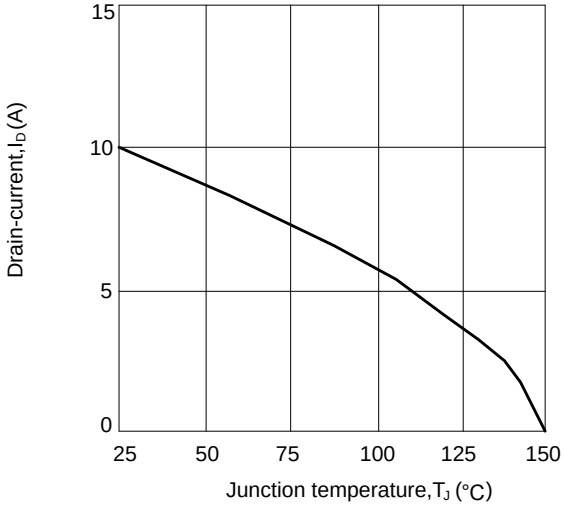


Figure 10:Drain current vs.junction temperature

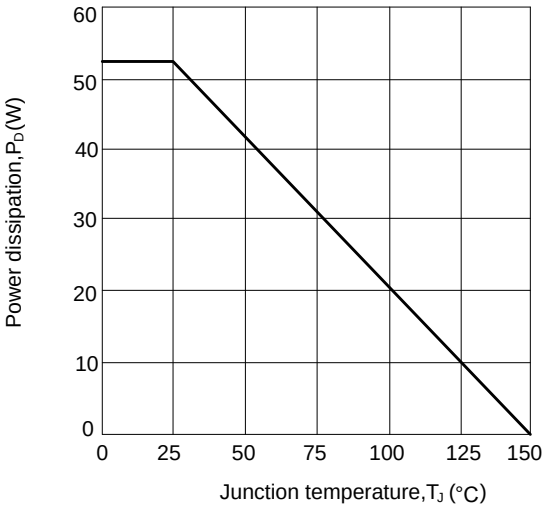


Figure 11:Power dissipation vs.junction temperature

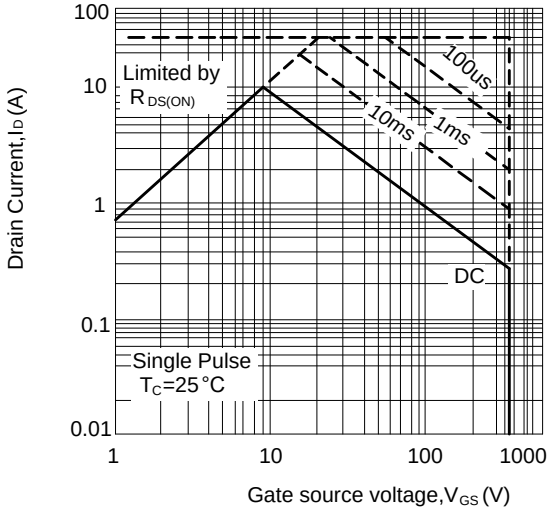


Figure 12:Safe operating area

■ TO-252 PACKAGE OUTLINE DIMENSIONS

